

DETAILED ACTION

Election/Restrictions

Claims 1, 2, 6, 9, 22-24 are allowable. Claims 15-21, previously withdrawn from consideration as a result of a restriction requirement, require all the limitations of an allowable claim. Pursuant to the procedures set forth in MPEP § 821.04(a), the restriction requirement between inventions of group A containing claims 1-2, 9 and group B containing claims 15-21, as set forth in the Office action mailed on 11/24/2009, is hereby withdrawn and claims 15-21 hereby rejoined and fully examined for patentability under 37 CFR 1.104. In view of the withdrawal of the restriction requirement, applicant(s) are advised that if any claim presented in a continuation or divisional application is anticipated by, or includes all the limitations of, a claim that is allowable in the present application, such claim may be subject to provisional statutory and/or nonstatutory double patenting rejections over the claims of the instant application. Once the restriction requirement is withdrawn, the provisions of 35 U.S.C. 121 are no longer applicable. See *In re Ziegler*, 443 F.2d 1211, 1215, 170 USPQ 129, 131-32 (CCPA 1971). See also MPEP § 804.01.

EXAMINER'S AMENDMENT

1. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with David Cho (48078) on 10/24/2011.

The following claims have been amended:

15. (currently amended) A process for assembling a flexible transponder including at least one electronic component made up of a chip provided with contacts on one of the faces of the chip, said contacts being set off on a conductive film constituting flat conductive areas that extend the

contacts of the chip in a plane over the chip, comprising: placing a first substrate on a work surface, placing the chip of the electronic component into a cavity of the first substrate, the conductive areas of the electronic component being applied against the surface of the first substrate, and

assembling the first substrate provided with the electronic component on a second substrate provided with conductive tracks, so that the conductive areas of the electronic component applied against the surface of the first substrate connect to the conductive tracks of the second substrate, wherein the conductive areas of the electronic component and the conductive tracks of the second substrate are in contact to achieve ~~[[an]]~~ a permanent electric connection via a pressure of application of the second substrate on the electronic component, and after the assembling, the conductive areas of the electronic component and the conductive tracks of the second substrate are configured to rub together when repeated stresses are exerted on the substrates.

19. (currently amended) A process for assembling a flexible transponder including at least one electronic component made up of a module including a set of flat contacts on one of the faces of the module, each contact of the set being linked with a contact area on the opposite face, comprising:

placing a first substrate on a work surface, placing the chip of the electronic component into a cavity provided with a window cut into a first substrate ~~with a thickness approximately~~

equal to that of the module, the set of flat contacts shows on the surface level of said first substrate, and

assembling the first substrate provided with the electronic component on a second substrate provided with conductive tracks, so that the conductive areas of the opposite face of the electronic component connect to the conductive tracks of the second substrate, wherein the conductive areas of the electronic component and the conductive tracks of the second substrate are in contact to achieve [[an]] a permanent electric connection via a pressure of application of the second substrate on the electronic component, and after the assembling, the conductive areas of the electronic component and the conductive tracks of the second substrate are configured to rub together when repeated stresses are exerted on the substrates.

Allowable Subject Matter

1. Claim(s) 1-2, 6, 9, 15-24 is/are allowed.
2. The following is a statement of reasons for the indication of allowable subject matter: Re claim 1, the closest prior art including DE 19645083 as cited previously failed to meet the claim limitations as currently amended. It does not provide any teachings such that the conductive areas of the electronic component and the conductive tracks of the substrate are configured to rub together when repeated stressed are exerted on the substrate while maintaining a permanent electric connection. Re independent claims 15 and 19 are allowable for similar reasons; particularly, the prior art fails to teach an assembling method such that after the assembling, the conductive areas of the electronic component and the conductive tracks of the second substrate are configured to rub together when repeated stresses are exerted on the substrates while maintaining a permanent electric connection.

3. As allowable subject matter has been indicated, applicant's reply must either comply with all formal requirements or specifically traverse each requirement not complied with. See 37 CFR 1.111(b) and MPEP § 707.07(a).

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to THIEN MAI whose telephone number is (571)272-8283. The examiner can normally be reached on Monday through Friday, 8:00 - 5:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Steve S. Paik can be reached on 571-272-2404. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Thien T Mai/
Primary Examiner, Art Unit 2887